CY54/74FCT240T
CY54/74FCT244T

8-Bit Buffers/Line Drivers

SCCS017 - May 1994 - Revised February 2000

Features

- **Function, pinout, and drive compatible with FCT and F logic**
- **FCT-D speed at 3.6 ns max. (Com'l FCT244 only), FCT-C speed at 4.1 ns max. (Com'l), FCT-A speed at 4.8 ns max. (Com'l)**
- **Reduced V_{OH} (typically = 3.3V) versions of equivalent FCT functions**
- **Edge-rate control circuitry for significantly improved noise characteristics**
- **Power-off disable feature**
- **ESD > 2000V**
- **Matched rise and fall times**
- **Fully compatible with TTL input and output logic levels**
- **Extended commercial range of –40°C to +85°C**
- **Sink current 64 mA (Com'l), 48 mA (Mil)**
  Source current 32 mA (Com'l), 12 mA (Mil)

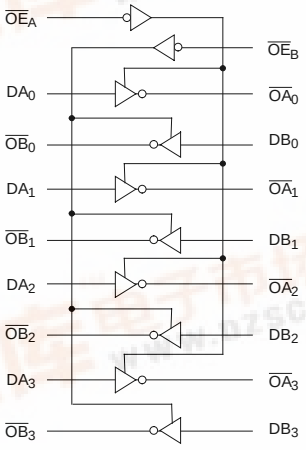
Functional Description

The FCT240T and FCT244T are octal buffers and line drivers designed to be employed as memory address drivers, clock drivers, and bus-oriented transmitters/receivers. The devices provide speed and drive capabilities equivalent to their fastest bipolar logic counterparts while reducing power consumption. The input and output voltage levels allow direct interface with TTL, NMOS, and CMOS devices without external components.

The outputs are designed with a power-off disable feature to allow for live insertion of boards.

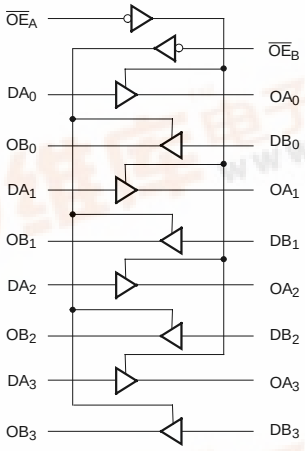
Logic Block Diagram

FCT240T



FCT240T–1

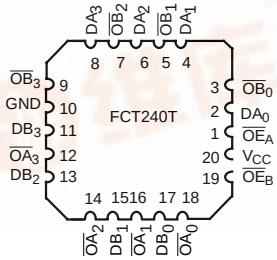
FCT244T



FCT240T–4

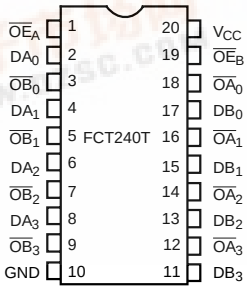
Pin Configurations

LCC
Top View



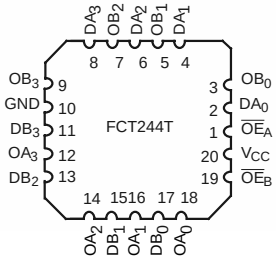
FCT240T–2

DIP/SOIC/QSOP
Top View



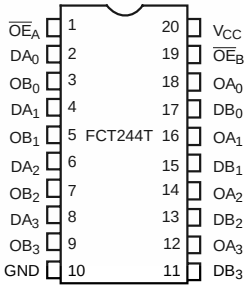
FCT240T–3

LCC
Top View



FCT240T–5

DIP/SOIC/QSOP
Top View



FCT240T–6

Function Table FCT240T[1]

Inputs			Output
$\overline{OE}_A$	$\overline{OE}_B$	D	
L	L	L	H
L	L	H	L
H	H	X	Z

Function Table FCT244T[1]

Inputs			Output
$\overline{OE}_A$	$\overline{OE}_B$	D	
L	L	L	L
L	L	H	H
H	H	X	Z

Maximum Ratings[2, 3]

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature .....–65°C to +150°C

Ambient Temperature with Power Applied.....–65°C to +135°C

Supply Voltage to Ground Potential .....–0.5V to +7.0V

DC Input Voltage.....–0.5V to +7.0V

DC Output Voltage .....–0.5V to +7.0V

DC Output Current (Maximum Sink Current/Pin).....120 mA

Power Dissipation 0.5W

Static Discharge Voltage.....>2001V (per MIL-STD-883, Method 3015)

Operating Range

Range	Speed	Ambient Temperature	V_{CC}
Commercial	DT	0°C to +70°C	5V ± 5%
Commercial	T, AT, CT	–40°C to +85°C	5V ± 5%
Military[4]	All	–55°C to +125°C	5V ± 10%

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions		Min.	Typ.[5]	Max.	Unit
V_{OH}	Output HIGH Voltage	V_{CC}=Min., I_{OH}=–32 mA	Com'l	2.0			V
		V_{CC}=Min., I_{OH}=–15 mA	Com'l	2.4	3.3		V
		V_{CC}=Min., I_{OH}=–12 mA	Mil	2.4	3.3		V
V_{OL}	Output LOW Voltage	V_{CC}=Min., I_{OL}=64 mA	Com'l		0.3	0.55	V
		V_{CC}=Min., I_{OL}=48mA	Mil		0.3	0.55	V
V_{IH}	Input HIGH Voltage			2.0			V
V_{IL}	Input LOW Voltage					0.8	V
V_H	Hysteresis[6]	All inputs			0.2		V
V_{IK}	Input Clamp Diode Voltage	V_{CC}=Min., I_{IN}=–18 mA			–0.7	–1.2	V
I_I	Input HIGH Current	V_{CC}=Max., V_{IN}=V_{CC}				5	µA
I_{IH}	Input HIGH Current	V_{CC}=Max., V_{IN}=2.7V				±1	µA
I_{IL}	Input LOW Current	V_{CC}=Max., V_{IN}=0.5V				±1	µA
I_{OZH}	Off State HIGH-Level Output Current	V_{CC} = Max., V_{OUT} = 2.7V				10	µA
I_{OZL}	Off State LOW-Level Output Current	V_{CC} = Max., V_{OUT} = 0.5V				–10	µA
I_{OS}	Output Short Circuit Current[7]	V_{CC}=Max., V_{OUT}=0.0V		–60	–120	–225	mA
I_{OFF}	Power-Off Disable	V_{CC}=0V, V_{OUT}=4.5V				±1	µA

Notes:

1. H = HIGH Voltage Level. L = LOW Voltage Level. X = Don't Care.
2. Unless otherwise noted, these limits are over the operating free-air temperature range.
3. Unused inputs must always be connected to an appropriate logic voltage level, preferably either V_{CC} or ground.
4. T_A is the "instant on" case temperature.
5. Typical values are at V_{CC}=5.0V, T_A=+25°C ambient.
6. This parameter is specified but not tested.
7. Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample and hold techniques are preferable in order to minimize internal chip heating and more accurately reflect operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

Capacitance[6]

Parameter	Description	Typ.[5]	Max.	Unit
C_{IN}	Input Capacitance	5	10	pF
C_{OUT}	Output Capacitance	9	12	pF

Power Supply Characteristics

Parameter	Description	Test Conditions	Typ.[5]	Max.	Unit
I_{CC}	Quiescent Power Supply Current	V_{CC}=Max., $V_{IN}\leq$0.2V, $V_{IN}\geq V_{CC}$–0.2V	0.1	0.2	mA
ΔI_{CC}	Quiescent Power Supply Current (TTL inputs)	V_{CC}=Max., V_{IN}=3.4V,[8] f_1=0, Outputs Open	0.5	2.0	mA
I_{CCD}	Dynamic Power Supply Current[9]	V_{CC}=Max., One Input Toggling, 50% Duty Cycle, Outputs Open, $\overline{OE}_1$=$\overline{OE}_2$=GND, $V_{IN}\leq$0.2V or $V_{IN}\geq V_{CC}$–0.2V	0.06	0.12	mA/MHz
I_C	Total Power Supply Current[10]	V_{CC}=Max., 50% Duty Cycle, Outputs Open, One Bit Toggling at f_1=10 MHz, $\overline{OE}_1$=$\overline{OE}_2$=GND, $V_{IN}\leq$0.2V or $V_{IN}\geq V_{CC}$–0.2V	0.7	1.4	mA
		V_{CC}=Max., 50% Duty Cycle, Outputs Open, One Bit Toggling at f_1=10 MHz, $\overline{OE}_1$=$\overline{OE}_2$=GND, V_{IN}=3.4V or V_{IN}=GND	1.0	2.4	mA
		V_{CC}=Max., 50% Duty Cycle, Outputs Open, Eight Bits Toggling at f_1=2.5 MHz, $\overline{OE}_1$=$\overline{OE}_2$=GND, $V_{IN}\leq$0.2V or $V_{IN}\geq V_{CC}$–0.2V	1.3	2.6[11]	mA
		V_{CC}=Max., 50% Duty Cycle, Outputs Open, Eight Bits Toggling at f_1=2.5 MHz, $\overline{OE}_1$=$\overline{OE}_2$=GND, V_{IN}=3.4V or V_{IN}=GND	3.3	10.6[11]	mA

Notes:

8. Per TTL driven input (V_{IN}=3.4V); all other inputs at V_{CC} or GND.
9. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
10. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$
    $I_C = I_{CC}+\Delta I_{CC}D_HN_T+I_{CCD}(f_0/2 + f_1N_1)$
    I_{CC} = Quiescent Current with CMOS input levels
    ΔI_{CC} = Power Supply Current for a TTL HIGH input (V_{IN}=3.4V)
    D_H = Duty Cycle for TTL inputs HIGH
    N_T = Number of TTL inputs at D_H
    I_{CCD} = Dynamic Current caused by an input transition pair (HLH or LHL)
    f_0 = Clock frequency for registered devices, otherwise zero
    f_1 = Input signal frequency
    N_1 = Number of inputs changing at f_1
    All currents are in milliamps and all frequencies are in megahertz.
11. Values for these conditions are examples of the I_{CC} formula. These limits are specified but not tested.

Switching Characteristics Over the Operating Range

Parameter	Description	FCT240T				FCT240AT				Unit	Fig. No.[13]
		Military		Commercial		Military		Commercial			
		Min.[12]	Max.	Min.[12]	Max.	Min.[12]	Max.	Min.[12]	Max.		
t_{PLH} t_{PHL}	Propagation Delay Data to Input	1.5	9.0	1.5	8.0	1.5	5.1	1.5	4.8	ns	1, 2
t_{PZH} t_{PZL}	Output Enable Time	1.5	10.5	1.5	10.0	1.5	6.5	1.5	6.2	ns	1, 7, 8
t_{PHZ} t_{PLZ}	Output Disable Time	1.5	10.0	1.5	9.5	1.5	5.9	1.5	5.6	ns	1, 7, 8

Parameter	Description	FCT240CT				Unit	Fig. No.[13]
		Military		Commercial			
		Min.[12]	Max.	Min.[12]	Max.		
t_{PLH} t_{PHL}	Propagation Delay Data to Input	1.5	4.7	1.5	4.3	ns	1, 2
t_{PZH} t_{PZL}	Output Enable Time	1.5	5.7	1.5	5.0	ns	1, 7, 8
t_{PHZ} t_{PLZ}	Output Disable Time	1.5	4.6	1.5	4.5	ns	1, 7, 8

Parameter	Description	FCT244T				FCT244AT				Unit	Fig. No.[13]
		Military		Commercial		Military		Commercial			
		Min.[12]	Max.	Min.[12]	Max.	Min.[12]	Max.	Min.[12]	Max.		
t_{PLH} t_{PHL}	Propagation Delay Data to Input	1.5	7.0	1.5	6.5	1.5	5.1	1.5	4.6	ns	1, 3
t_{PZH} t_{PZL}	Output Enable Time	1.5	8.5	1.5	8.0	1.5	6.5	1.5	6.2	ns	1, 7, 8
t_{PHZ} t_{PLZ}	Output Disable Time	1.5	7.5	1.5	7.0	1.5	5.9	1.5	5.6	ns	1, 7, 8

Parameter	Description	FCT244CT				FCT244DT		Unit	Fig. No.[13]
		Military		Commercial		Commercial			
		Min.[12]	Max.	Min.[12]	Max.	Min.[12]	Max.		
t_{PLH} t_{PHL}	Propagation Delay Data to Input	1.5	4.6	1.5	4.1	1.5	3.6	ns	1, 3
t_{PZH} t_{PZL}	Output Enable Time	1.5	6.5	1.5	5.8	1.5	4.8	ns	1, 7, 8
t_{PHZ} t_{PLZ}	Output Disable Time	1.5	5.7	1.5	5.2	1.5	4.0	ns	1, 7, 8

Notes:

12. Minimum limits are specified but not tested on Propagation Delays.
13. See “Parameter Measurement Information” in the General Information section.

Ordering Information—FCT240T

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
4.3	CY74FCT240CTSOC/SOCT	S5	20-Lead (300-Mil) Molded SOIC	Commercial
	CY74FCT240CTQCT	Q5	20-Lead (150-Mil) QSOP	
4.8	CY74FCT240ATSOC/SOCT	S5	20-Lead (300-Mil) Molded SOIC	Commercial
	CY74FCT240ATQCT	Q5	20-Lead (150-Mil) QSOP	
5.1	CY54FCT240ATDMB	D6	20-Lead (300-Mil) CerDIP	Military
	CY54FCT240ATLMB	L61	20-Pin Square Leadless Chip Carrier	
8.0	CY74FCT240TSOC/SOCT	S5	20-Lead (300-Mil) Molded SOIC	Commercial
	CY74FCT240TQCT	Q5	20-Lead (150-Mil) QSOP	
9.0	CY54FCT240TDMB	D6	20-Lead (300-Mil) CerDIP	Military

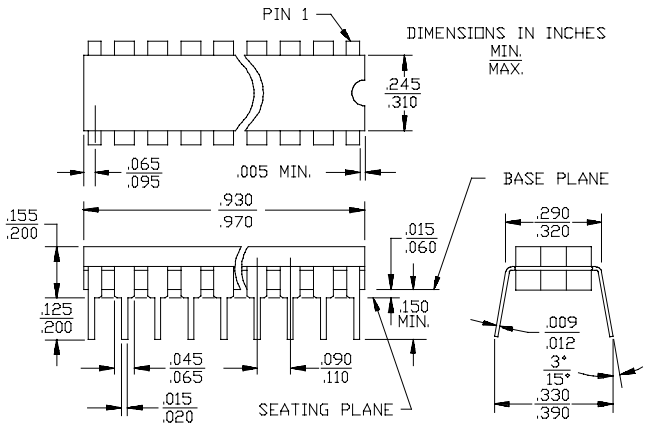
Ordering Information—FCT244T

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
3.6	CY74FCT244DTQCT	Q5	20-Lead (150-Mil) QSOP	Commercial
	CY74FCT244DTSOC/SOCT	S5	20-Lead (300-Mil) Molded SOIC	
4.1	CY74FCT244CTSOC/SOCT	S5	20-Lead (300-Mil) Molded SOIC	Commercial
	CY74FCT244CTQCT	Q5	20-Lead (150-Mil) QSOP	
4.6	CY54FCT244CTDMB	D6	20-Lead (300-Mil) CerDIP	Military
4.6	CY74FCT244ATPC	P5	20-Lead (300-Mil) Molded DIP	Commercial
	CY74FCT244ATSOC/SOCT	S5	20-Lead (300-Mil) Molded SOIC	
	CY74FCT244ATQCT	Q5	20-Lead (150-Mil) QSOP	
5.1	CY54FCT244ATDMB	D6	20-Lead (300-Mil) CerDIP	Military
	CY54FCT244ATLMB	L61	20-Pin Square Leadless Chip Carrier	
6.5	CY74FCT244TSOC/SOCT	S5	20-Lead (300-Mil) Molded SOIC	Commercial
	CY74FCT244TQCT	Q5	20-Lead (150-Mil) QSOP	
7.0	CY54FCT244TDMB	D6	20-Lead (300-Mil) CerDIP	Military
	CY54FCT244TLMB	L61	20-Pin Square Leadless Chip Carrier	

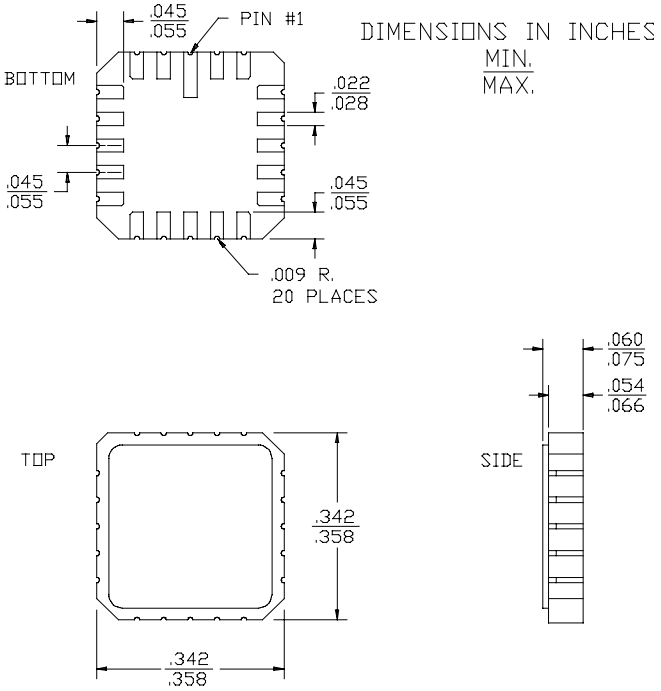
Shaded areas contain preliminary information.

Package Diagrams

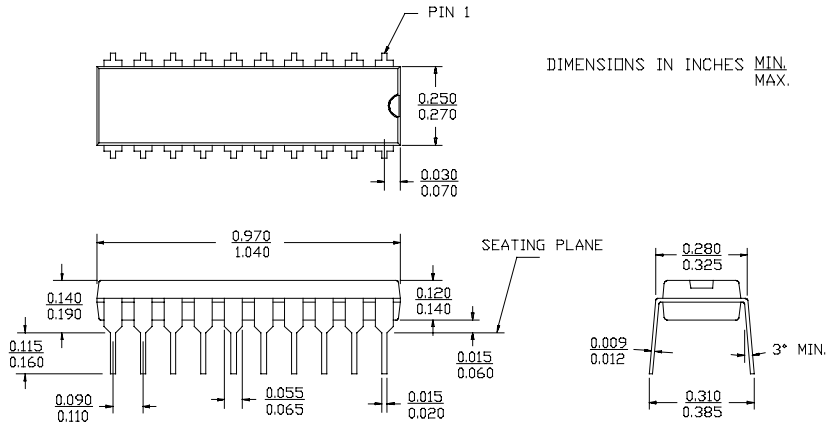
20-Lead (300-Mil) CerDIP D6
MIL-STD-1835 D- 8 Config.A



20-Pin Square Leadless Chip Carrier L61
MIL-STD-1835 C-2A

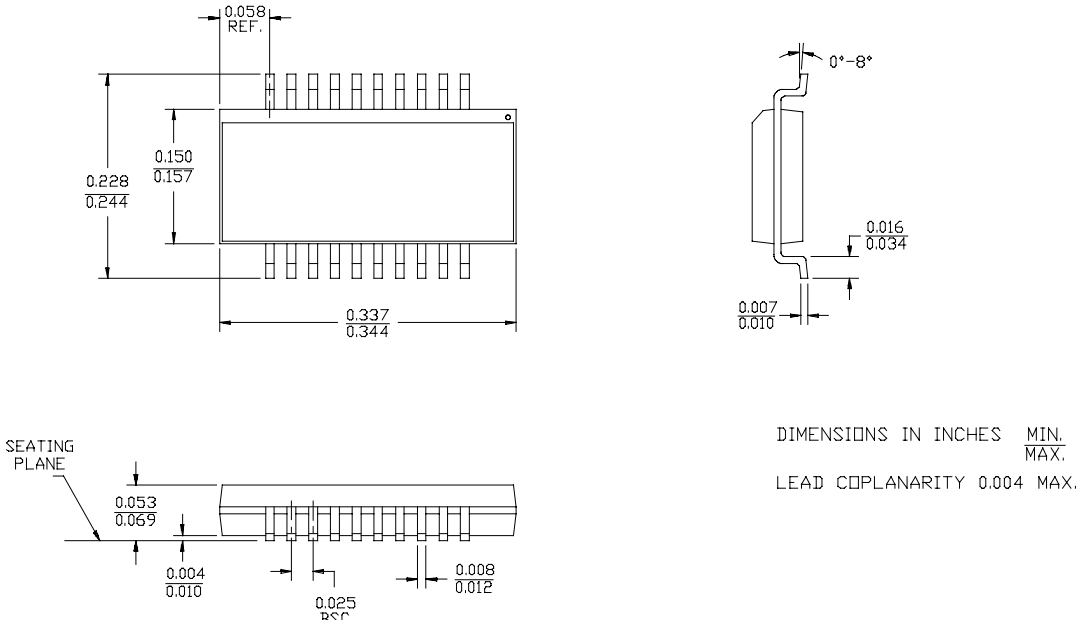


20-Lead (300-Mil) Molded DIP P5

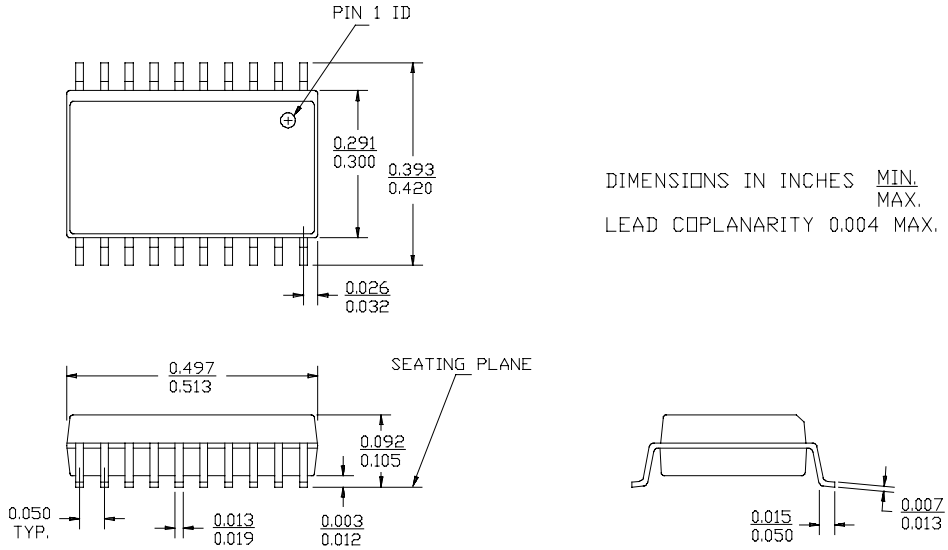


Package Diagrams (continued)

20-Lead Quarter Size Outline Q5



20-Lead (300-Mil) Molded SOIC S5



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